

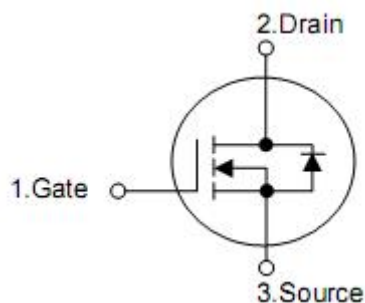
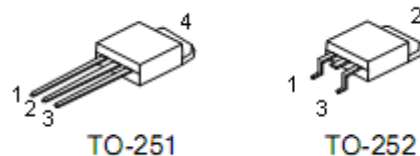
## 1. Description

KIA7610A designed by the trench processing techniques to achieve extremely low on-resistance. Additional features of this design are a 175 °C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in DC-DC Converters and Off-line UPS and a wide variety of other applications.

## 2. Features

- n  $R_{DS(on)} = 32m\Omega$
- n Low On-resistance
- n Fast switching
- n 100% avalanche tested
- n Repetitive avalanche allowed up to  $t_{jmax}$
- n LeAT-Free, RoHS compliant

## 3. Pin configuration



Pin	Function
1	Gate
2	Drain
3	Source
4	Drain

#### 4. Absolute maximum ratings

(T<sub>C</sub>=25°C , unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-source voltage	V <sub>DSS</sub>	100	V
Drain current continuous	I <sub>D</sub>	T <sub>C</sub> =25°C	25
		T <sub>C</sub> =100°C	16
Drain current pulsed (note1)	I <sub>DM</sub>	100	A
Gate-source voltage	V <sub>GSS</sub>	±20	V
Single Pulse avalanche energy (note2)	E <sub>AS</sub>	90	mJ
Power dissipation	P <sub>D</sub>	60	W
Maximum junction temperature	T <sub>J</sub>	175	°C
Operating and storage temperature range	T <sub>STG</sub>	-55~+175	°C
Diode continuous forward current (note1)	I <sub>S</sub>	25	A

#### 5. Thermal characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal resistance junction-case	R <sub>thJC</sub>	-	1.8	°C/W
Thermal resistance junction-ambient	R <sub>thJA</sub>	-	75	

## 6. Electrical characteristics

(T<sub>J</sub>=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units	
Off characteristics							
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	-	-	V	
Zero gate voltage drain current	I <sub>DSS</sub>	T <sub>C</sub> =25°C	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	-	-	10	μA
		T <sub>C</sub> =125°C	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	-	-	100	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA	
On characteristics							
Gate threshold voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.5	3.0	V	
Static drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =14A	-	32	38	mΩ	
Dynamic characteristics							
Input capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=1MHz	-	2020	-	pF	
Output capacitance	C <sub>OSS</sub>		-	450	-	pF	
Reverse transfer capacitance	C <sub>RSS</sub>		-	255	-	pF	
Switching characteristics							
Turn-on delay time	t <sub>D(ON)</sub>	V <sub>DD</sub> =50V, R <sub>G</sub> =6.8Ω, I <sub>D</sub> =1A, V <sub>GS</sub> =10V, R <sub>L</sub> =25Ω,	-	25	-	ns	
Rise time	t <sub>R</sub>		-	19	-	ns	
Turn-off delay time	t <sub>D(OFF)</sub>		-	58	-	ns	
Fall time	t <sub>F</sub>		-	75	-	ns	
Total gate charge	Q <sub>G</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V I <sub>D</sub> =10A	-	55	-	nC	
Gate-source charge	Q <sub>GS</sub>		-	13.6	-	nC	
Gate-drain charge	Q <sub>GD</sub>		-	11.2	-	nC	
Drain-source diode characteristics							
Continuous drain-source current	I <sub>S</sub>		-	-	25	A	
Drain-source diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =12A	-	0.82	1.3	V	
Reverse recovery time	t <sub>RR</sub>	V <sub>GS</sub> =0V, I <sub>F</sub> =12A, di <sub>F</sub> /dt=100A/μs	-	60	-	nS	
Reverse recovery charge	Q <sub>RR</sub>		-	95	-	nC	

Note: 1. Pulse width ≤300μs, duty cycle ≤2% pulse width limited by maximum junction temperature

2. Limited by T<sub>Jmax</sub>, starting T<sub>J</sub>=25°C, L=0.5mH, R<sub>G</sub>=25Ω, I<sub>AS</sub>=19A, V<sub>GS</sub>=10V

**7. Test circuits and waveforms**

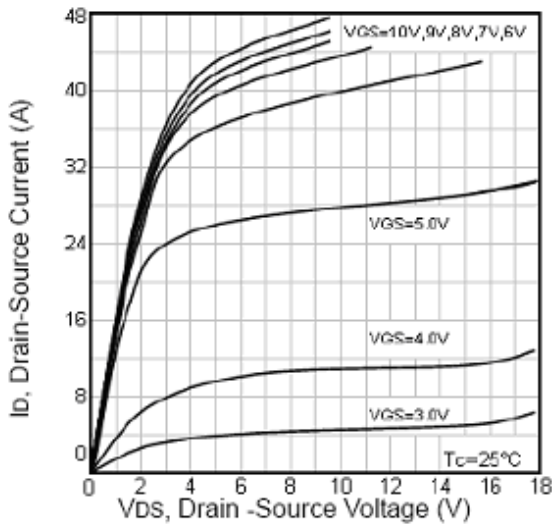


Fig1. Typical Output Characteristics

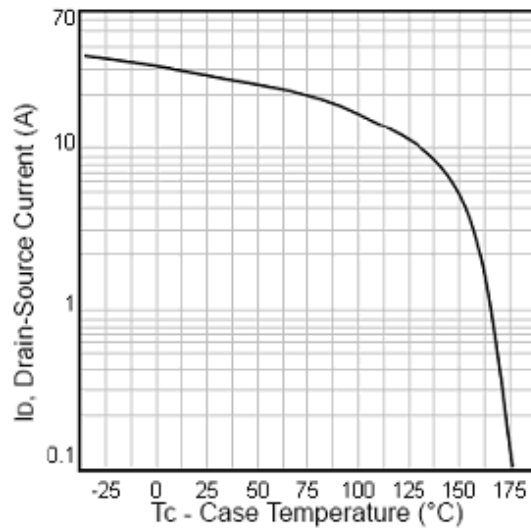


Fig2. Maximum Drain Current Vs. Case Temperature

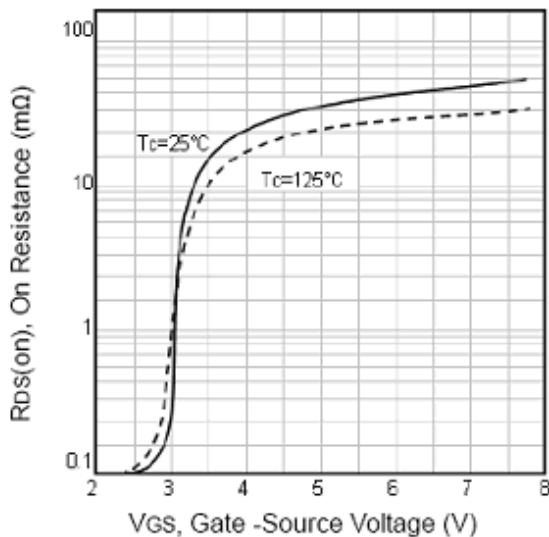


Fig3. Typical On Resistance Vs. Gate-Source

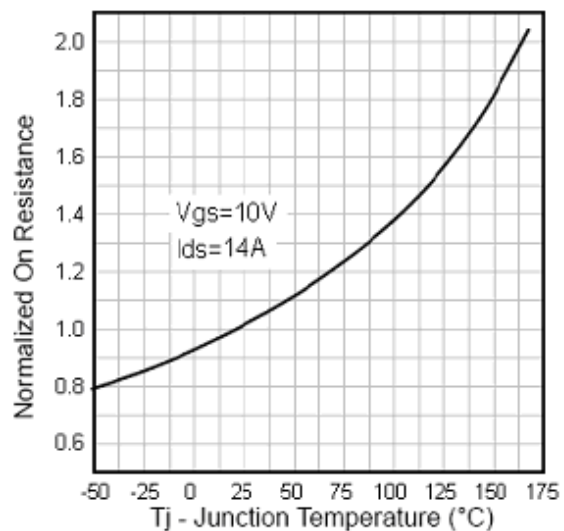


Fig4. Normalized On-Resistance Vs. Temperature

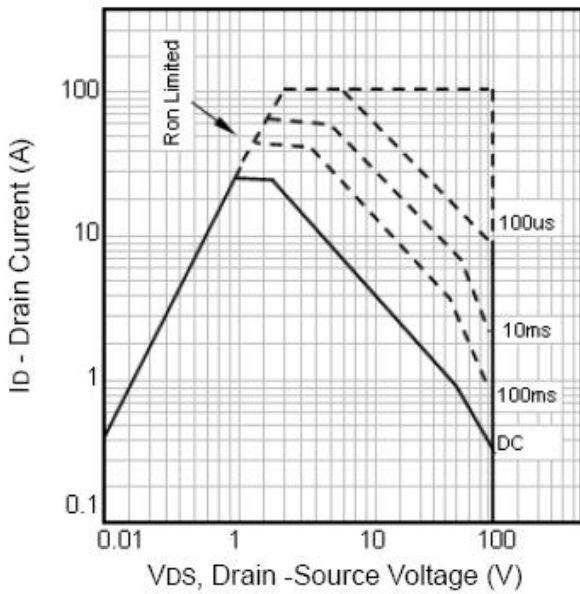


Fig5. Maximum Safe Operating Area

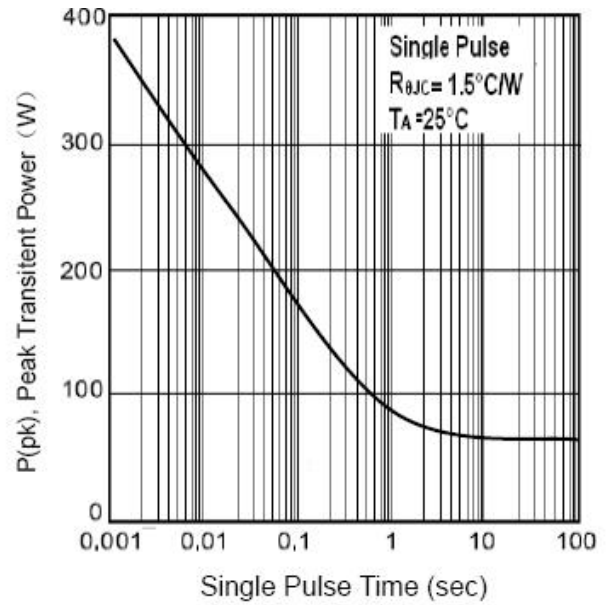


Fig6. Typical Transient Power

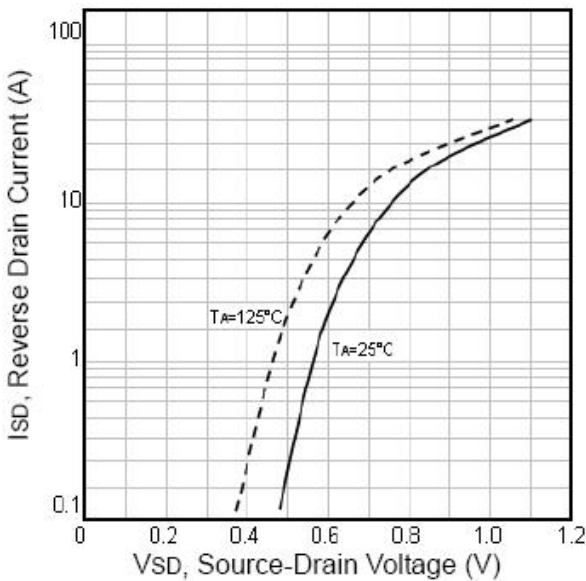


Fig7. Typical Source-Drain Diode Forward Voltage

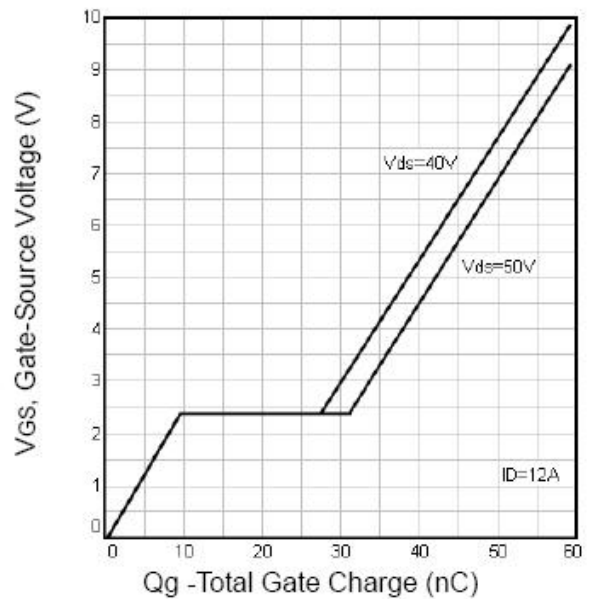


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

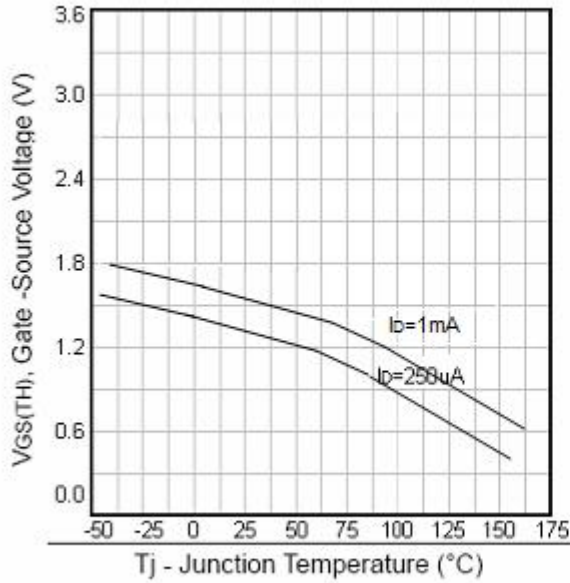


Fig9. Threshold Voltage Vs. Temperature

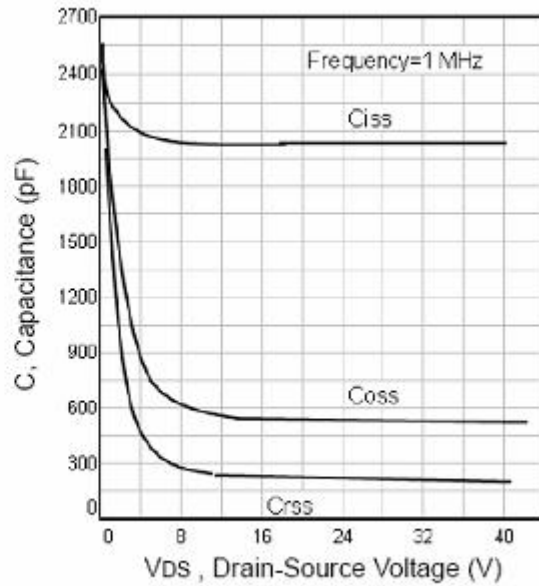


Fig10. Typical Capacitance Vs.Drain-Source Voltage

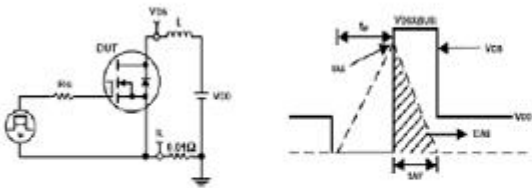


Fig11. Unclamped Inductive Test Circuit and waveforms

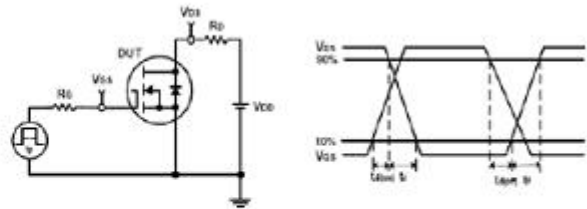


Fig12. Switching Time Test Circuit and waveforms